

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1. (Currently Amended) A method of assembling a packaged high frequency circuit module including the steps of :
 - providing a ceramic substrate having one or more elongate stub walls projecting from a planar surface thereof;
 - firing the ceramic substrate;
 - processing the fired substrate until the planar surfaces surface of the one or more elongate stub walls [[are]] is uniform and parallel;
 - applying a conductive adhesive to the processed surfaces of the one or more stub walls; and
 - placing a housing lid over the substrate, the lid having one or more members projecting from a planar surface thereof so that the one or more members align with the one or more stub walls of the substrate to form a composite structure.

2. (Currently Amended) The method according to claim 1, wherein the one or more stub walls extend extends, at least partially, around the periphery of the planar surface of the substrate.

3. (Previously Presented) The method according to claim 1, wherein the one or more stub walls project from an inner wall track of the substrate.

4. (Previously Presented) The method according to claim 1, wherein the projection of the one or more stub walls from the planar surface of the substrate is proportional to predetermined surface distortion values for the substrate.

5. (Previously Presented) The method according to claim 1, wherein processing a surface of the substrate comprises one or more of grinding, lapping or polishing the surface.

6. (Previously Presented) The method according to claim 1, further comprising the steps of

applying pressure to the composite structure and curing the conductive adhesive.

7. (Withdrawn) A method according to claim 1, wherein the elongate stub walls project from the upper planar surface of the substrate.

8. (Withdrawn) A method according to claim 1, wherein the elongate stub walls project from the lower planar surface of the substrate.

9. (Withdrawn) A high frequency circuit module comprising:
 - a ceramic substrate having one or more elongate stub walls projecting from a planar surface thereof, the planar surfaces of the stub walls having been processed so that they are uniform and parallel;
 - a conductive adhesive layer on the processed surfaces of the stub walls; and
 - a housing lid mounted over the substrate, the lid having one or more members projecting from a planar surface thereof so that the members align with the stub walls of the substrate to form a composite structure.
10. (Previously Presented) The method according to claim 2, wherein one or more stub walls project from an inner wall track of the substrate.
11. (Previously Presented) The method according to claim 2, wherein the projection of the one or more stub walls from the planar surface of the substrate is proportional to predetermined surface distortion values for the substrate.
12. (Previously Presented) The method according to claim 3, wherein the projection of the one or more stub walls from the planar surface of the substrate is proportional to predetermined surface distortion values for the substrate.
13. (Previously Presented) The method according to claim 2, wherein processing a surface of the substrate comprises one or more of grinding, lapping or polishing the surface.

14. (Previously Presented) The method according to claim 3, wherein processing a surface of the substrate comprises one or more of grinding, lapping or polishing the surface.

15. (Previously Presented) The method according to claim 4, wherein processing a surface of the substrate comprises one or more of grinding, lapping or polishing the surface.

16. (New) The method according to claim 1, wherein the one or more elongate stub walls are integrally formed on the ceramic substrate.

17. (New) The method according to claim 1, wherein the one or more elongate stub walls are formed on the ceramic substrate such that during the processing step, processing tools make contact with the surfaces of the one or more stub walls and not with the planar surface of the substrate in order to minimize the area of the substrate that is processed.